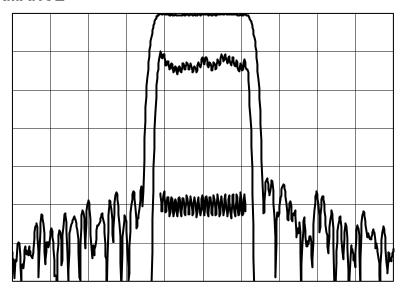
TYPICAL PERFORMANCE



Horizontal: 2.5 MHz/div

Vertical (from top):

Magnitude Magnitude

Group Delay Deviation

10 150

dB/div dB/div ns/div

SPECIFICATION

Parameter	Min	Тур	Max	Units		
All electrical specifications apply over the full -10°C to +50°C operating range and						
include allowance for all manufacturing tolerances						
Center Frequency F _C ¹	114.88	115	115.12	MHz		
1 dB Bandwidth ²	5.6	6.08		MHz		
3 dB Bandwidth ²	6.0	6.44		MHz		
40 dB Bandwidth ²		7.75	8.2	MHz		
Stopband Rejection, 25 MHz to 100 MHz	45	58		dB		
Stopband Rejection, 130 MHz to 1000 MHz	45	53		dB		
Minimum Insertion Loss		18.9	20	dB		
Passband Amplitude Variation, F _C ± 2.8 MHz ³		0.6	8.0	dB p-p		
Passband Group Delay Variation, F _C ± 2.8 MHz		100	150	ns p-p		
Absolute Delay		2.0	2.1	μs		
Input VSWR, F _C ± 2.8 MHz ⁴		1.55	1.8	: 1		
Output VSWR, F _C ± 2.8 MHz ⁴		1.3	1.8	: 1		
Maximum Input Level	20			dBm		
Source and Load Impedance	50		Ω			
Operating Temperature Range	-10		+50	°C		
Storage Temperature Range	-45		+85	°C		

Notes:

- 1. Defined as the mean of the 10dB frequencies.
- 2. dB levels are taken to be relative to the insertion loss.
- 3. Excludes final roll-offs to the 1dB points. Note that 'Passband Amplitude Variation' includes Ripple (fast variations) and Slope (slow variations).
- 4. When matched as indicated on Page 3.

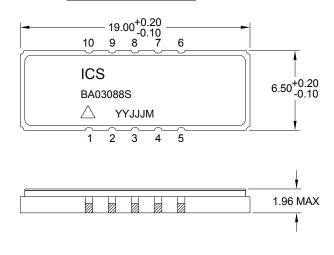
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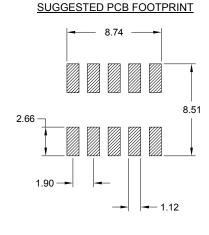
Integrated Circuit Systems • Surface Acoustic Wave Products 324 Clark Street, Worcester, MA 01606, USA • Phone 508-852-5400 • Fax 508-852-8456

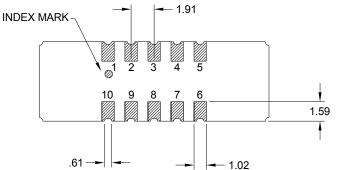


PACKAGE AND SUGGESTED PCB FOOTPRINT

PACKAGE INFORMATION







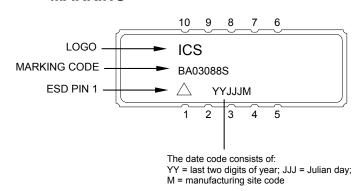
PIN NO.	DESCRIPTION
10	INPUT
5	OUTPUT
1,2,3,4,6,7,8,9	GROUND

NOTES: DIMENSIONS SHOWN ARE NOMINAL IN MILLIMETERS. ALL TOLERANCES ARE ±0.15MM EXCEPT OVERALL LENGTH

AND WIDTH

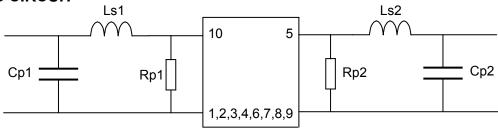
Package Material: Body: Al_2O_3 ceramic Lid: Kovar, Ni plated Terminations: Au plating 0.5-1.0 um, over a 2-6 um Ni plating

MARKING



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Component values in 50Ω : Rp1 = 430 Ω (Minimum inductor Q = 45) Rp2 = 300 Ω

Ls1 = 68 nH Cp1 = 56 pF Ls2 = 68 nH Cp2 = 56 pF

Notes:

- 1. Optimum values may differ from these when using a different fixture or board layout. The values shown here are intended as a guide only.
- 2. Required component tolerances resistors ±5%, inductors ±2%, capacitors ±5%.

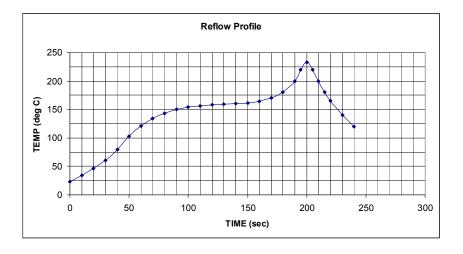
MAXIMUM RATINGS

Parameter	Min	Max	Units
Operating Temperature Range	-10	+50	°C
Storage Temperature Range	-45	+85	°C
Input Power Level		20	dBm
D. C. Voltage between Each Terminal		15	V



PHYSICAL AND ENVIRONMENTAL CHARACTERISTICS

Parameter	Qualification Conditions
Life Testing	High temperature bake at +85 °C for 168 hours.
	MIL-STD 883, Method 1010:
Temperature Cycling	-40 °C to +85 °C, 10 cycles, 10 minutes dwell at
	temperature extremes
Vibration	MIL-STD-202, Method 201A:
	10 to 55 Hz, double amplitude of 0.06" for 2 hours in each
	axis.
Mechanical Shock	MIL-STD-883, Method 2002, Test Condition B:
	1500 g, 3 impacts each axis
Solder Heat Resistance and Reflow Condition	Peak temperature 240+/-5 °C for 10 seconds.
	Pre-heat: 150-170 °C for 60 to 90 seconds.
	Peak dwell: over 200 °C for 23 to 26 seconds.
	Handling: Class 1 per MIL-STD-1686
	Reflow Profile is shown at the bottom of this table.
Lead Integrity	MIL-STD 883 Method 2004, Condition D
	8 oz for 30 seconds.
Solderability	MIL-STD-883 Method 2003:
	245 °C +/-5 °C; 95% coverage; no steam aging
Hermeticity	MIL-STD 883 Method 1014:
	Condition A2 and Condition C (no bomb)
ESD Classification	Class I per MIL-STD-883 Method 3015
Precautions	Do not subject devices to ultrasonic cleaning, which may
	cause deterioration and destruction of the device.



ISO 9001 Registered

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